



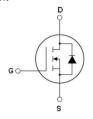
N-Channel Super Junction Power MOSFET II

General Description

The series of devices use advanced super junction technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- ◆ New technology for high voltage device
- ◆ Low on-resistance and low conduction losses
- ◆ Small package
- ◆ Ultra Low Gate Charge cause lower driving requirements
- ◆ 100% Avalanche Tested
- ◆ ROHS compliant





Schematic diagram

TO-220

Application

- ◆ Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- ◆ Uninterruptible Power Supply (UPS)

VDS	650	V
Rds(on) max	540	mΩ
ID	8	А

Package Marking And Ordering Information

Device	Device Package	Marking
MJ65R540	TO-220	MJ65R540

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	MJ65R540	Unit
Drain-Source Voltage (Ves=0V)	VDS	650	V
Gate-Source Voltage (Vps=0V)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	ID (DC)	8	Α
Continuous Drain Current at Tc=100°C	ID (DC)	5.2	А
Pulsed drain current (Note 1)	IDM (pluse)	24	А
Maximum Power Dissipation (Tc=25°C)	Po	80	VV
Derate above 25°C	Po	0.64	W/°C
Single pulse avalanche energy (Note 2)	Eas	185	mJ
Avalanche current (Note 1)	lar	4	А
Repetitive Avalanche energy, tar limited by T _{jmax} (Note 1)	Ear	0.4	mJ

Parameter	Symbol	MJ65R540	Unit
Drain Source voltage slope, V _{DS} ≤480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	TJ,Tsтg	-55+150	°C





Table 2. Thermal Characteristic

Parameter	Symbol	MJ65R540	Unit
Thermal Resistance, Junction-to-Case (Maximum)	RthJC	1.56	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	RthJA	62	°C/W

Table 3. Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
On/off states							
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250μA	650	-	-	V	
Zero Gate Voltage Drain Current (Tc=25°C)	loss	V _{DS} =650V,V _{GS} =0V	-	-	1	μΑ	
Zero Gate Voltage Drain Current (Tc=125°C)	loss	V _{DS} =650V,V _{GS} =0V	-	-	100	μΑ	
Gate-Body Leakage Current	lgss	V _{GS} =±30V,V _{DS} =0V	-	-	±100	nA	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	2.5	3	3.5	V	
Drain-Source On-State Resistance	Rds(on)	Vgs=10V,ID=4A	-	480	540	mΩ	
Dynamic Characteristics							
Forward Transconductance	g FS	V _{DS} =20V,I _D =4A	-	5.5	-	S	
Input Capacitance	Cies		-	680	-	PF	
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V F=1.0MHz	-	58	-	PF	
Reverse Transfer Capacitance	Crss		-	4	-	PF	
Total Gate Charge	Qg		-	14.5	22	nC	
Gate-Source Charge	Qgs	V _{DS} =480V,I _D =8A V _{GS} =10V	-	2.8	-	nC	
Gate-Drain Charge	Qgd		-	5.5	-	nC	
Intrinsic gate resistance	Rg	f=1 MHz open drain	-	2	-	Ω	
Switching times							
Turn-on Delay Time	t _{d(on)}		-	5.5	-	nS	
Turn-on Rise Time	tr	VDD=380V,ID=4A	-	3.5	-	nS	
Turn-Off Delay Time	t _{d(off)}	R _G =12Ω,V _{GS} =10V	-	55	75	nS	
Turn-Off Fall Time	tr		-	6.5	10	nS	
Source- Drain Diode Characteristics	'						
Source-drain current (Body Diode)	Isp		-	-	8	А	
Pulsed Source-drain current (Body Diode)	Isdm	- Tc=25°C	-	-	23.4	А	
Forward On Voltage	Vsb	T _j =25°C,I _{SD} =8A,V _{GS} =0V	-	0.9	1.2	V	
Reverse Recovery Time	trr		-	220	-	nS	
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=8A di/dt=100A/µs	-	2.2	-	uC	
Peak reverse recovery current	Irrm		-	20	_	А	

lpr, Reverse Drain Current(A)

lb, Drain Current (A)

ADS(ON), Drain-Source

On-Resistance(Ω)

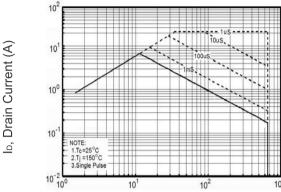




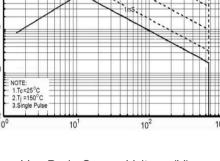
Notes

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
- $2.T_j = 25^{\circ}C, V_{DD} = 50V, V_{G} = 10V, R_{G} = 25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)







Vsp,Source-Drain Voltage(V)

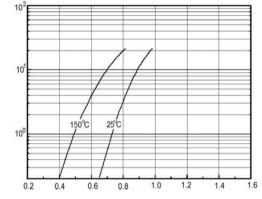


Figure 1 Safe operating area

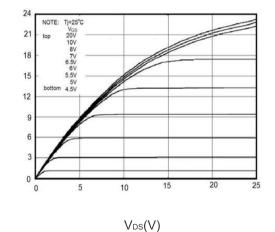


Figure 2 Source-Drain Diode Forward Voltage

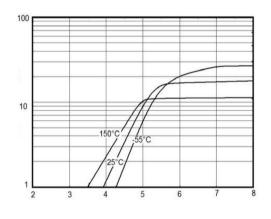
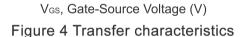
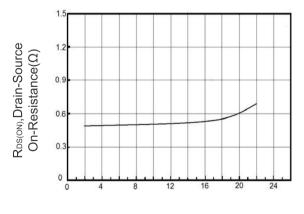
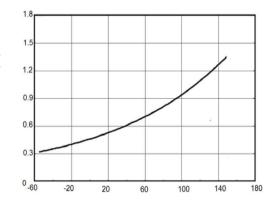


Figure 3 Output characteristics





ID, Drain Current (A) Figure 5 Static drain-source on resistance

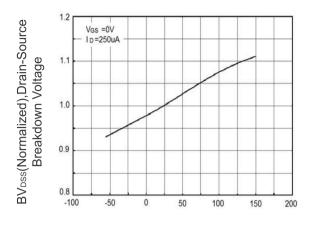


T_J, Junction Temperature (°C) Figure 6 RDS(ON) vs Junction Temperature

lo, Drain Current (A)

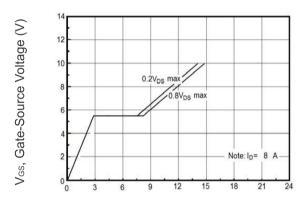
Capacitances(pF)





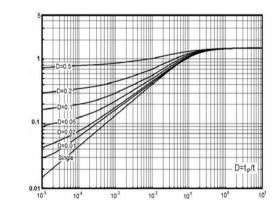
T_J, Junction Temperature (°C)

Figure 7 BVDSS vs Junction Temperature



Q_G,Total Gate Charge(nC)

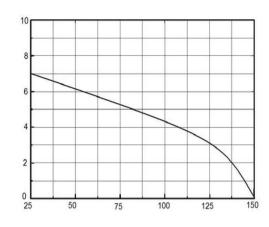
Figure 9 Gate charge waveforms



Zthuc, Thermal Respone

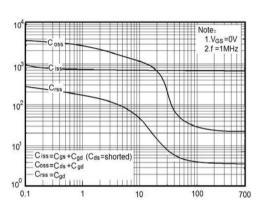
t₅,Square Wave Pulse(S)

Figure 11 Transient Thermal Impedance



Tc, Case Temperature (°C)

Figure 8 Maximum ID vs Junction Temperature



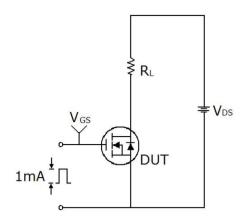
V_{DS}, Drain-Source Voltage (V)

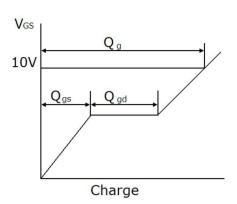
Figure 10 Capacitance



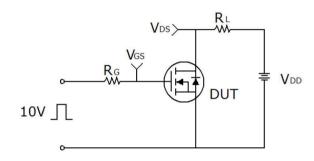


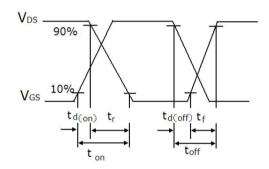
Test circuit



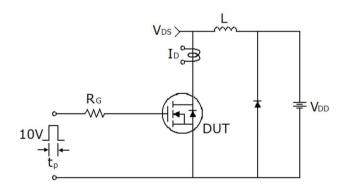


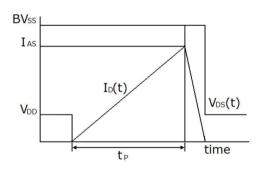
Gate charge test circuit & Waveform





Switch Time Test Circuit



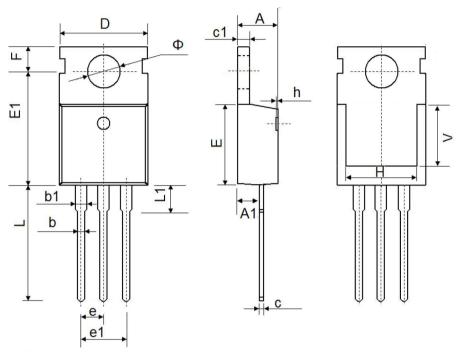


Unclamped Inductive Switching Test Circuit & Waveforms





TO-220-3L-C Package Information



Sumb al	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540 TYP.		0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.500 REF.		0.295 REF.		
Ф	3.400	3.800	0.134	0.150	





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